© Copyr	ial Composition right 2005. IPC, Bann onal and Pan-America	ockburn, Illinois. A	All rights reserved u ntions.	nder both	This docume level parts, th	ent is a declar he declaration	ration of t n encomp	he substances basses all low	within the er level mat	manufactur erials for wl	er listed ite hich the m	em. Not anufactu	e: if the item is a arer has engineer	an assembly with low ring responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Formation http://www.ipc.org/IPC-175x Distribution				e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mate					ous Materia	ials and Mfg Information				
Supplier Information															
Company name*	Company un	Company unique ID			Unique ID Authority					Response Date*					
onsemi											2024-04-25				
Contact Name	Title - Conta	Title - Contact			Phone - Contact*					Email - Contact*					
Product-Env-Stewards	Product Envi	Product Enviro Compliance			NA					Product-Env-Stewards@onsemi.com					
Authorized Representative*	Title - Repre	Title - Representative			Phone - Representative*				Email - Representative*						
Product-Env-Stewards	Product Envi	Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com						
Requester Item Num	Requester Item Number Mfr Ite		n Number Mfr Item Name			Effective Da	ate Ver	sion	Manufacturing Site		V	Veight*	UOM	Unit Type	
	FD3	FD3501MNTXG		VR13HC 8-Phase (M+N) Controller		2024-04-25 TV		TWU		7	0.13	mg	Each		
Manufacturing Proccess	Information					1	1						1		
Terminal Plating / Gr	tting / Grid Array Material Terminal I		Alloy J	J-STD-020 MSL Rating		Peak Process Body Temp		dy Temperatu	ature Max Time at Peak T		Temperature Number of Reflow Cycles		Cycles		
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		CU Alloy	CU Alloy 1			260		C	30		second	ls 3			
Comments															
vel 1 - maximum time at peal	k temperature durin	g soldering is 10-3	0 seconds												
or more information regardin	ng material composit	ion please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	8.68	mg	Supplier	Silicon (Si)	7440-21-3		8.68	mg
Die Attach	0.65	mg	Supplier	Isobornyl Methacrylate	7534-94-3		0.039	mg
			Supplier	Silver (Ag)	7440-22-4		0.5297	mg
			Supplier	Isobornyl Acrylate	5888-33-5		0.039	mg
			Supplier	Misc.	Proprietary Data		0.0032	mg
			Supplier	Tricyclo[5.2.1.02,6]decanedimethanol Diacrylate (C18H24O4)	42594-17-2		0.039	mg
Lead Frame	30.44	mg	Supplier	Silver (Ag)	7440-22-4		0.6088	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0365	mg
			Supplier	Iron (Fe)	7439-89-6		0.7153	mg
			Supplier	Copper (Cu)	7440-50-8		29.0702	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0091	mg
Mold Compound-Black	29.62	mg		Epoxy resin	proprietary data		1.481	mg
			Supplier	Phenolic Resin	Proprietary Data		0.6813	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		1.481	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1185	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.6813	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		25.177	mg
Plating	0.42	mg	Supplier	Palladium (Pd)	7440-05-3		0.0105	mg
			В	Nickel (Ni)	7440-02-0		0.399	mg
			Supplier	Gold (Au)	7440-57-5		0.0105	mg
Wire Bond - Au	0.32	mg	Supplier	Gold (Au)	7440-57-5		0.32	mg